

L4 ANSWER 1 OF 3 CAPLUS COPYRIGHT 2005 ACS on STN

AN 1987:600602 CAPLUS

DN 107:200602

ED Entered STN: 27 Nov 1987

TI Coating compositions

IN Washiyama, Junichiro; Motoyama, Takuhiko

PA Showa Denko K. K., Japan

SO Jpn. Kokai Tokkyo Koho, 7 pp.

CODEN: JKXXAF

DT Patent

LA Japanese

IC ICM C09D003-82

ICA C08L083-04

CC 42-10 (Coatings, Inks, and Related Products)

FAN.CNT 1

PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI JP 62124158	A2	19870605	JP 1985-264619	19851125 <--
PRAI JP 1985-264619		19851125		

CLASS

PATENT NO.	CLASS	PATENT FAMILY CLASSIFICATION CODES
JP 62124158	ICM	C09D003-82
	ICA	C08L083-04

AB Coating compns., heat- and chemical-resistant and useful on metals, ceramics, and plastics, contain ladder silicones and the siloxanes RO(SiR1R2O)_mR3 [R, R3 = H, Me, Et; R1, R2 = (halogenated) Me, Et, Pr, Ph; m = 1-2000]. A blend of silsesquioxane (GR 100) 270, Ph₂Si(OMe)₂ 30, and PhMe 700 g was coated on primed, sandblasted steel, dried at room temperature for 15 min, heated at 50° for 30 min and 90° for 30 min, cooled, recoated, and heated at 180° for 90 min. The 23-μ film showed no change after 1 h at 550°, after 50 h in 20% NaOH, concentrated H₂SO₄, AcOH, Me₂CO, or PhMe at 50°, or after 1000-h salt spray testing.

ST siloxane blend coating; silsesquioxane coating chem resistance; heat resistance siloxane coating; steel coating siloxane blend

IT Coating materials

(anticorrosive, silsesquioxane-siloxane blends as)

IT Coating materials

(chemical- and heat-resistant, silsesquioxane-siloxane blends as)

IT 78-62-6, Dimethyldiethoxysilane 6843-66-9, Diphenyldimethoxysilane
RL: USES (Uses)

(in siloxane coatings, chemical- and heat-resistant)

RN 78-62-6

RN 6843-66-9

L4 ANSWER 2 OF 3 WPIX COPYRIGHT 2005 THE THOMSON CORP on STN

AN 1987-195216 [28] WPIX

DNC C1987-081443

TI Coating compsn. with good heat and chemical resistance - contains a poly silicone resin and an organo siloxane cpd. e.g. di methyl di silanol.

DC A26 A82 G02 M13

PA (SHOW) SHOWA DENKO KK

CYC 1

PI JP 62124158 A 19870605 (198728)* 7 <--

ADT JP 62124158 A JP 1985-264619 19851125

PRAI JP 1985-264619 19851125

IC C08L083-04; C09D003-82

AB JP 62124158 A UPAB: 19930922

The compsn. contains (a) a silicone resin and (b) a organosiloxane cpd. of formula (I), where R₁, R₂ = methyl, ethyl, propyl or phenyl gp. opt. subst. with halogen; R₃, R₄ = H, methyl or ethyl gp.; n = 1-2000, pref. 1-200.

To prepare the compsn. 100 pts.weight of (a) and 0.1-30, pref. 1-20 pts.weight of (b) are dissolved in a solvent e.g. alcohol, ketone, aromatic hydrocarbon, ester and cellosolve.

ADVANTAGE - The compsn. for coating has good heat and chemical resistance and forms a coating film with no pin holes. It is used for coating the surfaces of metals, ceramics, plastics, etc.. (a) is shown by formula (II), where R5, R6 = methyl, ethyl butyl or phenyl gp. which may be substd. with halogen. n' = 3 to 200. (b) includes dimethyl dimethoxy (diethoxy)silane, dimethyl disilanol, diphenyl dimethoxy (diethoxy)silane, diphenyl silanol, methylphenyldimethoxy (diethoxy)silane, methylphenyl disilanol, etc..

O/O

FS CPI

FA AB

MC CPI: A06-A00E1; A08-D; A12-B01C; G02-A01A; M13-H05

L4 ANSWER 3 OF 3 JAPIO (C) 2005 JPO on STN

AN 1987-124158 JAPIO

TI COATING COMPOSITION

IN WASHIYAMA JUNICHIRO; MOTOYAMA TAKUHIKO

PA SHOWA DENKO KK

PI JP 62124158 A 19870605 Showa

AI JP 1985-264619 (JP60264619 Showa) 19851125

PRAI JP 1985-264619 19851125

SO PATENT ABSTRACTS OF JAPAN (CD-ROM), Unexamined Applications, Vol. 1987

IC ICM C09D003-82

ICA C08L083-04

AB PURPOSE: The titled composition having improved heat resistance and chemical resistance and good barrier properties to substrates free from pinhole, containing a ladder type silicone resin and a specific organosiloxane compound.

CONSTITUTION: The aimed composition containing (A) 100pts.weight ladder type silicone shown by formula I ($R<SB>5</SB>$ and $R<SB>6</SB>$ are methyl, ethyl, butyl, phenyl, or halogen atom-substituted group thereof; n' is 3~200) and (B) preferably 1~20pts. weight organosiloxane compound shown by formula II ($R<SB>1</SB>$ and $R<SB>2</SB>$ are methyl, ethyl, propyl, phenyl or halogen-substituted group thereof; $R<SB>3</SB>$ and $R<SB>4</SB>$ are H, methyl or ethyl; n is 1~2,000).

COPYRIGHT: (C)1987,JPO&Japio

=>